



# Material Composition Declaration

## EPC2218

Company Name	Efficient Power Conversion (EPC)	Issue Date:	9/9/2020
Contact Name:	Yanping Ma	Contact Title:	VP Quality
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Part Weight:	10.9 mg	Type of Product:	eGaN FET

Construction Element	Substance	CAS No. If Applicable	Weight	Mass	Sum	Mass
			(mg)	(%)	(%)	(ppm)
Chip	Silicon	7440-21-3	8.0749	73.7483	76.2735	737483
	Silicon oxide	7631-86-9	0.0266	0.2427		2427
	Silicon nitride	12033-89-5	0.0155	0.1412		1412
	Gallium nitride	25617-97-4	0.0385	0.3513		3513
	Aluminum	7429-90-5	0.1070	0.9769		9769
	Aluminum nitride	24304-00-5	0.0087	0.0796		796
	Titanium	7440-32-6	0.0015	0.0140		140
	Titanium nitride	25583-20-4	0.0104	0.0949		949
	Copper	7440-50-8	0.0036	0.0325		325
	Tungsten	7440-33-7	0.0039	0.0354		354
	Polyimide		0.0609	0.5566	5566	
Under Bump Metal	Titanium	7440-32-6	0.0013	0.0119	0.1300	119
	Nickel	7440-02-0	0.0000	0.0000		0
	Copper	7440-50-8	0.0129	0.1181		1181
Solder Bump	Copper	7440-50-8	0.1294	1.1815	23.5965	11815
	Nickel	7440-02-0	0.0772	0.7048		7048
	Tin	7440-31-5	2.3343	21.3195		213195
	Silver	7440-22-4	0.0428	0.3908		3908
Sum in total:			10.9493	100.0000	100.0000	1000000

**Note:**

The substance content disclosed herewith is approximate and is based on engineering calculation. Statements are based on our present knowledge and may subject to change at any time due to technical requirements and development. EPC may update this document without notification. Statement may not include information regarding the minute quantities of dopant and metal materials in the electrical devices contained within the finished product.